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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Presettable Counters

High-Performance Silicon-Gate CMOS

The MC74HC160A is identical in pinout to the LS160. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC160A is a programmable BCD counters with asynchronous Reset input.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 234 FETs or 58.5 Equivalent Gates
- These are Pb-Free Devices

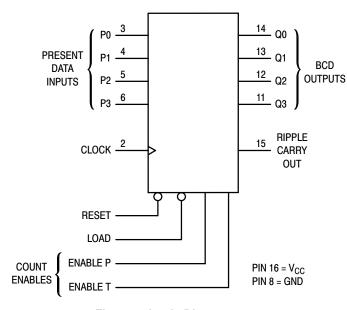


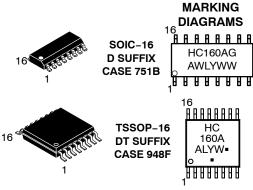
Figure 1. Logic Diagram

| Device | Count Mode | Reset Mode |
|--------|------------|--------------|
| HC160 | BCD | Asynchronous |



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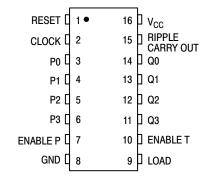


= Assembly Location

WL, L = Wafer Lot Year YY, Y WW, W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

FUNCTION TABLE

| | Inputs | | | | | |
|-------|--------|------|----------|----------|------------------|--|
| Clock | Reset* | Load | Enable P | Enable T | Q | |
| | L | Х | Х | Х | Reset | |
| | Н | L | Х | Х | Load Preset Data | |
| | Н | Н | Н | Н | Count | |
| | Н | Н | L | Х | No Count | |
| | Н | Н | Х | L | No Count | |

^{*}HC160 is an Asynchronous Reset Device.

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|------------------|--|-------------------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | -0.5 to +7.0 | V |
| V _{in} | DC Input Voltage (Referenced to GND) | -0.5 to V _{CC} + 0.5 | V |
| V _{out} | DC Output Voltage (Referenced to GND) | -0.5 to V _{CC} + 0.5 | V |
| l _{in} | DC Input Current, per Pin | ±20 | mA |
| l _{out} | DC Output Current, per Pin | ±25 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | ±50 | mA |
| P _D | Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package† | 750 500 | mW |
| T _{stg} | Storage Temperature | -65 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating - SOIC Package: - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | | | Max | Unit |
|------------------------------------|--|-------------------------------------|-------------|--------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | | | 6.0 | V |
| V _{in} , V _{out} | DC Input Voltage, Output Voltage (Referenced to GND) | | | V_{CC} | V |
| T _A | Operating Temperature, All Package Types | | -55 | +125 | °C |
| t _r , t _f | (Figure 3) V _C | C = 2.0 V C = 4.5 V C = 6.0 V | 0 0 0 | 1000 500 400 | ns |

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or $V_{\rm CC}$). Unused outputs must be left open.

H = High Level

L = Low Level

X = Don't Care

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| | | | | | Guaranteed Limit | | |
|-----------------|---|---|--------------------------|---------------------------|---------------------------|---------------------------|----------|
| Symbol | Parameter | Test Conditions | V _{CC} V | – 55 to 25°C | ≤ 85 °C | ≤ 125°C | Unit |
| V _{IH} | Minimum High-Level Input Voltage | V_{out} = 0.1 V or V_{CC} - 0.1 V $ I_{out} \le 20 \mu A$ | 2.0 3.0 4.5 6.0 | 1.5 2.1 3.15 4.2 | 1.5 2.1 3.15 4.2 | 1.5 2.1 3.15 4.2 | V |
| V _{IL} | Maximum Low-Level Input Voltage | V_{out} = 0.1 V or V_{CC} – 0.1 V $ I_{out} \le 20 \mu A$ | 2.0 3.0 4.5 6.0 | 0.5 0.9 1.35 1.8 | 0.5 0.9 1.35 1.8 | 0.5 0.9 1.35 1.8 | V |
| V _{OH} | Minimum High-Level Output Voltage | $V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$ | 2.0 4.5 6.0 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | V |
| | | $\begin{tabular}{l l l l l l l l l l l l l l l l l l l $ | 3.0 4.5 6.0 | 2.48 3.98 5.48 | 2.34 3.84 5.34 | 2.20 3.70 5.20 | |
| V _{OL} | Maximum Low-Level Output Voltage | $V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$ | 2.0 4.5 6.0 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | V |
| | | $\begin{aligned} V_{in} = V_{IH} \text{ or } V_{IL} & & I_{out} \leq 2.4 \text{ m} \\ & & I_{out} \leq 4.0 \text{ mA} \\ & & I_{out} \leq 5.2 \text{ mA} \end{aligned}$ | 3.0 4.5 6.0 | 0.26 0.26 0.26 | 0.33 0.33 0.33 | 0.40 0.40 0.40 | |
| l _{in} | Maximum Input Leakage Current | V _{in} = V _{CC} or GND | 6.0 | ± 0.1 | ± 1.0 | ± 1.0 | μΑ |
| Icc | Maximum Quiescent Supply Current (per Package) | $V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$ | 6.0 | 4 | 40 | 160 | μΑ |

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

| | | | Gu | | | |
|--|--|----------------------|-----------------|-----------------|-----------------|------|
| Symbol | Parameter | V _{CC} V | – 55 to 25°C | ≤ 85 °C | ≤ 125°C | Unit |
| f _{max} | Maximum Clock Frequency (50% Duty Cycle)* (Figures 3 and 8) | 2.0 4.5 6.0 | 6.0 30 35 | 4.8 24 28 | 4.0 20 24 | MHz |
| t _{PLH} | Maximum Propagation Delay, Clock to Q (Figures 3 and 8) | 2.0 4.5 6.0 | 170 34 29 | 215 43 37 | 255 51 43 | ns |
| t _{PHL} | | 2.0 4.5 6.0 | 205 41 35 | 255 51 43 | 310 62 53 | |
| t _{PHL} | Maximum Propagation Delay, Reset to Q (HC160A Only) (Figures 4 and 8) | 2.0 4.5 6.0 | 210 42 36 | 265 53 45 | 315 63 54 | ns |
| t _{PLH} | Maximum Propagation Delay, Enable T to Ripple Carry Out (Figures 5 and 8) | 2.0 4.5 6.0 | 160 32 27 | 200 40 34 | 240 48 41 | ns |
| t _{PHL} | | 2.0 4.5 6.0 | 195 39 33 | 245 49 42 | 295 59 50 | |
| t _{PLH} | Maximum Propagation Delay, Clock to Ripple Carry Out (Figures 3 and 8) | 2.0 4.5 6.0 | 175 35 30 | 220 44 37 | 265 53 45 | ns |
| t _{PHL} | | 2.0 4.5 6.0 | 215 43 37 | 270 54 46 | 325 65 55 | |
| t _{PHL} | Maximum Propagation Delay, Reset to Ripple Carry Out (HC160A Only) (Figures 4 and 8) | 2.0 4.5 6.0 | 220 44 37 | 275 55 47 | 330 66 56 | ns |
| t _{TLH} , t _{THL} | Maximum Output Transition Time, Any Output (Figures 3 and 8) | 2.0 4.5 6.0 | 75 15 13 | 95 19 16 | 110 22 19 | ns |
| C _{in} | Maximum Input Capacitance | - | 10 | 10 | 10 | pF |

^{*}Applies to noncascaded/nonsynchronously clocked configurations only. With synchronously cascaded counters, (1) Clock to Ripple Carry Out propagation delays, (2) Enable T or Enable P to Clock setup times, and (3) Clock to Enable T or Enable P hold times determine f_{max}. However, if Ripple Carry Out of each stage is tied to the Clock of the next stage (nonsynchronously clocked), the f_{max} in the table above is applicable. See Applications Information in this data sheet.

| | | Typical @ 25°C, V _{CC} = 5.0 V | |
|-----------------|--|---|----|
| C _{PD} | Power Dissipation Capacitance (Per Package)* | 60 | рF |

^{*}Used to determine the no–load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

TIMING REQUIREMENTS (Input $t_r = t_f = 6 \text{ ns}$)

| | | | Gu | ıaranteed Li | mit | |
|---------------------------------|--|-------------------|--------------------|--------------------|--------------------|------|
| Symbol | Parameter | V _{CC} | – 55 to 25°C | ≤ 85 °C | ≤ 125°C | Unit |
| t _{su} | Minimum Setup Time, Preset Data Inputs to Clock (Figure 6) | 2.0 4.5 6.0 | 150 30 26 | 190 38 33 | 225 45 38 | ns |
| t _{su} | Minimum Setup Time, Load to Clock (Figure 6) | 2.0 4.5 6.0 | 135 27 23 | 170 34 29 | 205 41 35 | ns |
| t _{su} | Minimum Setup Time, Enable T or Enable P to Clock (Figure 7) | 2.0 4.5 6.0 | 200 40 34 | 250 50 43 | 300 60 51 | ns |
| t _h | Minimum Hold Time, Clock to Preset Data Inputs (Figure 6) | 2.0 4.5 6.0 | 50 10 9 | 65 13 11 | 75 15 13 | ns |
| t _h | Minimum Hold Time, Clock to Load (Figure 6) | 2.0 4.5 6.0 | 3 3 3 | 3 3 3 | 3 3 3 | ns |
| t _h | Minimum Hold Time, Clock to Enable T or Enable P (Figure 7) | 2.0 4.5 6.0 | 3 3 3 | 3 3 3 | 3 3 3 | ns |
| t _{rec} | Minimum Recovery Time, Reset Inactive to Clock (Figure 4) | 2.0 4.5 6.0 | 125 25 21 | 155 31 26 | 190 38 32 | ns |
| t _{rec} | Minimum Recovery Time, Load Inactive to Clock (Figure 6) | 2.0 4.5 6.0 | 125 25 21 | 155 31 26 | 190 38 32 | ns |
| t _w | Minimum Pulse Width, Clock (Figure 3) | 2.0 4.5 6.0 | 80 16 14 | 100 20 17 | 120 24 20 | ns |
| t _w | Minimum Pulse Width, Reset (Figure 4) | 2.0 4.5 6.0 | 80 16 14 | 100 20 17 | 120 24 20 | ns |
| t _r , t _f | Maximum Input Rise and Fall Times (Figure 3) | 2.0 4.5 6.0 | 1000 500 400 | 1000 500 400 | 1000 500 400 | ns |

FUNCTION DESCRIPTION

The HC160A is a programmable 4-bit synchronous counters that feature parallel Load, synchronous or asynchronous Reset, a Carry Output for cascading, and count-enable controls. The HC160A is a BCD counter with asynchronous Reset.

INPUTS

Clock (Pin 2)

The internal flip-flops toggle and the output count advances with the rising edge of the Clock input. In addition, control functions, such as loading occur with the rising edge of the Clock input.

Preset Data Inputs P0, P1, P2, P3 (Pins 3, 4, 5, 6)

These are the data inputs for programmable counting. Data on these pins may be synchronously loaded into the internal flip-flops and appear at the counter outputs. P0 (pin 3) is the least-significant bit and P3 (pin 6) is the most-significant bit.

OUTPUTS

Q0, Q1, Q2, Q3 (Pins 14, 13, 12, 11)

These are the counter outputs (BCD or binary). Q0 (pin 14) is the least-significant bit and Q3 (pin 11) is the most-significant bit.

Ripple Carry Out (Pin 15)

When the counter is in its maximum state (1001 for the BCD counters or 1111 for the binary counters), this output goes high, providing an external look—ahead carry pulse that may be used to enable successive cascaded counters. Ripple Carry Out remains high only during the maximum count state. The logic equation for this output is:

Ripple Carry Out = Enable T • Q0 • $\overline{Q1}$ • $\overline{Q2}$ • Q3 for BCD counters

CONTROL FUNCTIONS

Resetting

A low level on the Reset pin (pin 1) resets the internal flip-flops and sets the outputs (Q0 through Q3) to a low level. The HC160A resets asynchronously.

Loading

With the rising edge of the Clock, a low level on Load (pin 9) loads the data from the Preset Data Input pins (P0, P1, P2, P3) into the internal flip-flops and onto the output pins, Q0 through Q3. The count function is disabled as long as Load is low.

Although the HC160A is a BCD counters, they may be programmed to any state. If they are loaded with a state disallowed in BCD code, they will return to their normal count sequence within two clock pulses (see the Output State Diagram).

Count Enable/Disable

These devices have two count-enable control pins: Enable P (pin 7) and Enable T (pin 10). The devices count when these two pins and the Load pin are high. The logic equation is:

Count Enable = Enable P • Enable T • Load

The count is either enabled or disabled by the control inputs according to Table 1. In general, Enable P is a count-enable control; Enable T is both a count-enable and a Ripple-Carry Output control.

Table 1. COUNT ENABLE/DISABLE

| Contr | ol Inputs | Result at Outputs | | | |
|-------|-----------|-------------------|----------|--|--|
| Load | Enable P | Enable T | Q0 – Q3 | Ripple Carry Out | |
| Н | Н | Н | Count | High when Q0 - Q3 are max- | |
| L | Н | Н | No Count | imum* | |
| Х | L | Н | No Count | High when Q0 - Q3 are max- imum* | |
| Х | Х | L | No Count | L | |

^{*}Q0 through Q3 are maximum for the HC160A when Q3 Q2 Q1 Q0 = 1001

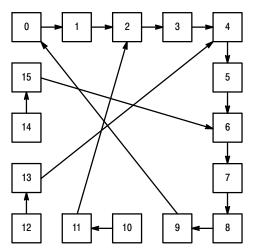


Figure 2. Output State Diagrams HC160A BCD Counters

SWITCHING WAVEFORMS

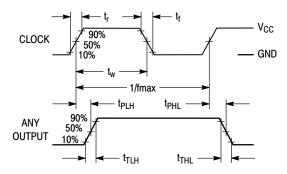


Figure 3.

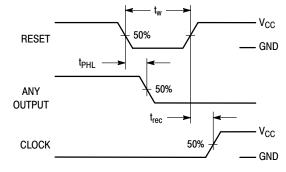


Figure 4.

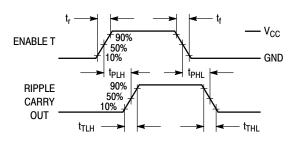
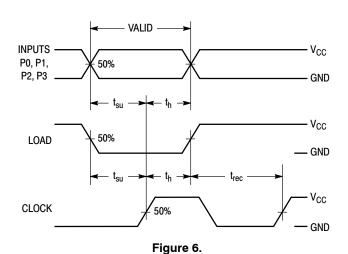
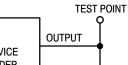


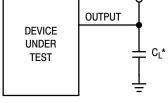
Figure 5.



VALID ENABLE T V_{CC} 50% OR **ENABLE P** GND V_{CC} 50% CLOCK – GND

Figure 7.





TEST CIRCUIT

*Includes all probe and jig capacitance

Figure 8.

MC74HC160A BCD Counter with Asynchronous Reset Qob LOAD LOAD Q0 Q1D LOAD LOAD Q1 Q2 C LOAD CLOAD Q3 V_{CC} = PIN 16 GND = PIN 8 The flip-flops shown in the circuit diagrams are Toggle-Enable flip-flops. A Toggle-Enable flip-flop is a combination of a D flip-flop and a T flip-flop. When loading data from Preset inputs P0, P1, P2, and P3, the Load signal is used to disable the Toggle input (Tn) of the flip-flop. The logic level at the Pn input is then clocked to the Q output of the flip-flop on the next rising edge of the clock. A logic zero on the Reset device input forces the internal clock (C) high and resets the Q

output of the flip-flop low.

LOAD

Sequence illustrated in waveforms:

- 1. Reset outputs to zero.
- 2. Preset to BCD seven.
- 3. Count to eight, nine, zero, one, two, and three.
- 4. Inhibit.

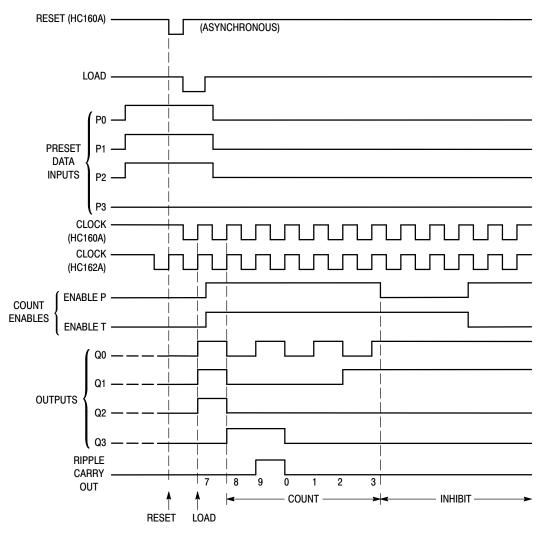
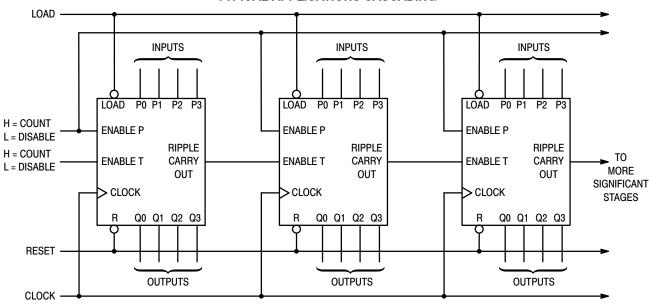


Figure 9. MC74HC160A Timing Diagram

TYPICAL APPLICATIONS CASCADING



 $NOTE: \quad \text{When used in these cascaded configurations the clock } f_{\text{max}} \text{ guaranteed limits may not apply. Actual performance will depend } f_{\text{max}} \text{ guaranteed limits may not apply. Actual performance will depend } f_{\text{max}} \text{ guaranteed limits may not apply. } f_{\text{m$ on number of stages. This limitation is due to set up times between Enable (Port) and Clock.

INPUTS INPUTS INPUTS LOAD -ENABLE P -ENABLE T -LOAD P0 P1 P2 P3 P0 P1 P2 P3 LOAD P0 P1 P2 P3 LOAD **ENABLE P ENABLE P ENABLE P RIPPLE RIPPLE RIPPLE ▶** T0 ENABLE T **CARRY ENABLE T CARRY CARRY ENABLE T** MORE OUT OUT OUT SIGNIFICANT CLOCK -> CLOCK > CLOCK > CLOCK STAGES Q0 Q1 Q2 Q3 Q0 Q1 Q2 Q3 Q0 Q1 Q2 Q3 RESET -**OUTPUTS OUTPUTS OUTPUTS**

Figure 10. N-Bit Synchronous Counters

Figure 11. Nibble Ripple Counter

ORDERING INFORMATION

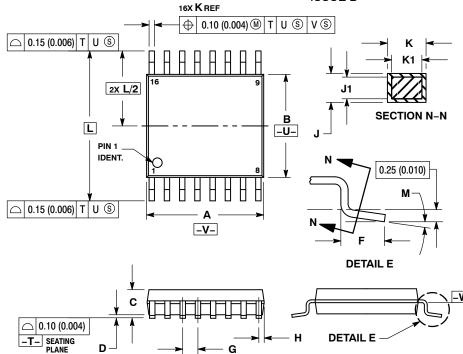
| Device | Package | Shipping [†] |
|-----------------|----------------------|-----------------------|
| MC74HC160ADG | SOIC-16 (Pb-Free) | 48 Units / Rail |
| MC74HC160ADR2G | SOIC-16 (Pb-Free) | 2500 Tape & Reel |
| MC74HC160ADTG | TSSOP-16* | 96 Units / Rail |
| MC74HC160ADTR2G | TSSOP-16* | 2500 Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}This package is inherently Pb-Free.

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** CASE 948F-01 **ISSUE B**



NOTES:

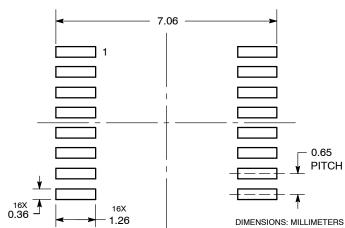
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE PETERMINED AT DATUM PLANE -W-.

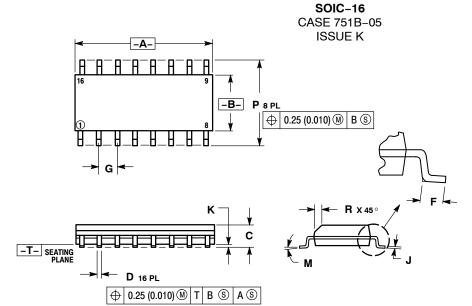
| | JIMILIAED | AI DAIL | | |
|-----|-----------|---------|-----------|-------|
| | MILLIN | IETERS | INC | HES |
| DIM | MIN | MAX | MIN | MAX |
| Α | 4.90 | 5.10 | 0.193 | 0.200 |
| В | 4.30 | 4.50 | 0.169 | 0.177 |
| С | - | 1.20 | | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 | BSC | 0.026 BSC | |
| Н | 0.18 | 0.28 | 0.007 | 0.011 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 | | 0.252 | BSC |
| Z | ٥° | 8° | o ° | 8° |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

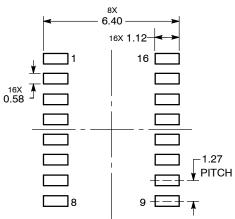


NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
 V14 5M 1982
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| | MILLIN | MILLIMETERS | | HES |
|-----|--------|-------------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 9.80 | 10.00 | 0.386 | 0.393 |
| В | 3.80 | 4.00 | 0.150 | 0.157 |
| С | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 | 1.27 BSC | | BSC |
| J | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0 ° | 7° | 0 ° | 7° |
| P | 5.80 | 6.20 | 0.229 | 0.244 |
| R | 0.25 | 0.50 | 0.010 | 0.019 |

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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